



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re the Application of: **Miwa KOZAWA et al.**

Group Art Unit: **1752**

Application Number: **10/629,806**

Examiner: **Sin J. Lee**

Filed: **July 30, 2003**

Confirmation Number: **9494**

For: **RESIST PATTERN THICKENING MATERIAL, PROCESS FOR
FORMING RESIST PATTERN, AND PROCESS FOR
MANUFACTURING SEMICONDUCTOR DEVICE**

Attorney Docket Number: **030923**

Customer Number: **38834**

AMENDMENT

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

July 20, 2006

Sir:

This paper is filed in response to the Office Action dated April 24, 2006.

Amendments to the Claims begin on page 2 of this paper.

Remarks begin on page 8 of this paper.